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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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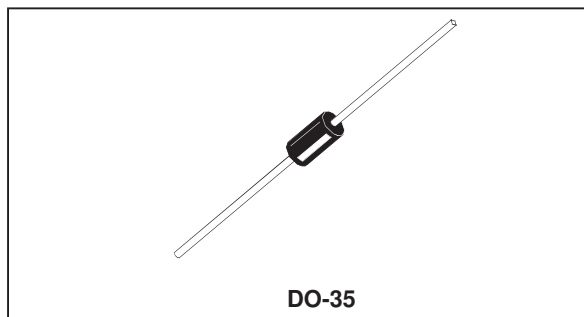


**1N5711**

## SMALL SIGNAL SCHOTTKY DIODE

### DESCRIPTION

Metal to silicon junction diode featuring high break-down, low turn-on voltage and ultrafast switching. Primarily intended for high level UHF/VHF detection and pulse application with broad dynamic range. Matched batches are available on request



### ABSOLUTE RATINGS (limiting values)

Symbol	Parameter		Value	Unit
$V_{RRM}$	Repetitive Peak Reverse Voltage		70	V
$I_F$	Forward Continuous Current*	$T_a = 25^\circ\text{C}$	15	mA
$P_{tot}$	Power Dissipation*	$T_a = 25^\circ\text{C}$	430	mW
$T_{stg}$ $T_j$	Storage and Junction Temperature Range		- 65 to 200 - 65 to 200	$^\circ\text{C}$
$T_L$	Maximum Lead Temperature for Soldering during 10s at 4mm from Case		230	$^\circ\text{C}$

### THERMAL RESISTANCE

Symbol	Test Conditions	Value	Unit
$R_{th(j-a)}$	Junction-ambient*	400	$^\circ\text{C/W}$

### ELECTRICAL CHARACTERISTICS

#### STATIC CHARACTERISTICS

Symbol	Test Conditions		Min.	Typ.	Max.	Unit
$V_{BR}$	$T_{amb} = 25^\circ\text{C}$	$I_R = 10\mu\text{A}$	70			V
$V_F^{**}$	$T_{amb} = 25^\circ\text{C}$	$I_F = 1\text{mA}$			0.41	V
	$T_{amb} = 25^\circ\text{C}$	$I_F = 15\text{mA}$			1	
$I_R^{**}$	$T_{amb} = 25^\circ\text{C}$	$V_R = 50\text{V}$			0.2	$\mu\text{A}$

#### DYNAMIC CHARACTERISTICS

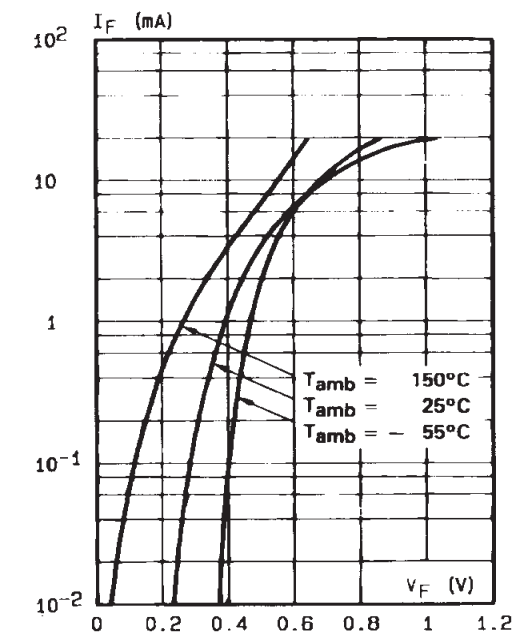
Symbol	Test Conditions			Min.	Typ.	Max.	Unit
C	$T_{amb} = 25^\circ\text{C}$	$V_R = 0\text{V}$	$f = 1\text{MHz}$			2	pF
$\tau$	$T_{amb} = 25^\circ\text{C}$	$I_F = 5\text{mA}$	Krakauer Method			100	ps

\* On infinite heatsink with 4mm lead length

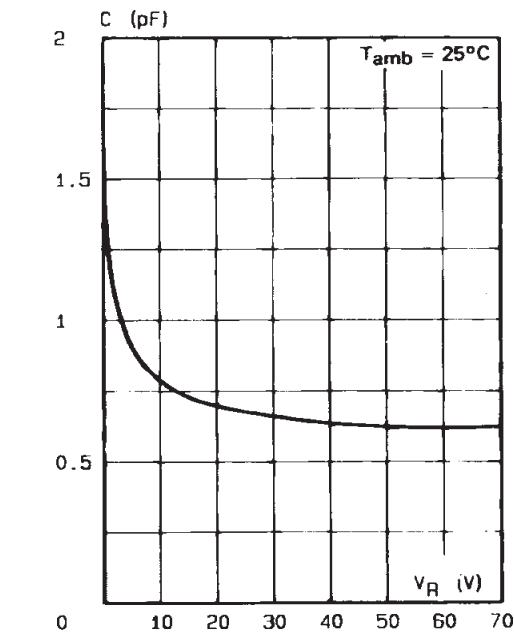
\*\* Pulse test:  $t_p \leq 300\mu\text{s}$   $\delta < 2\%$ .

Matched batches available on request. Test conditions (forward voltage and/or capacitance) according to customer specification.

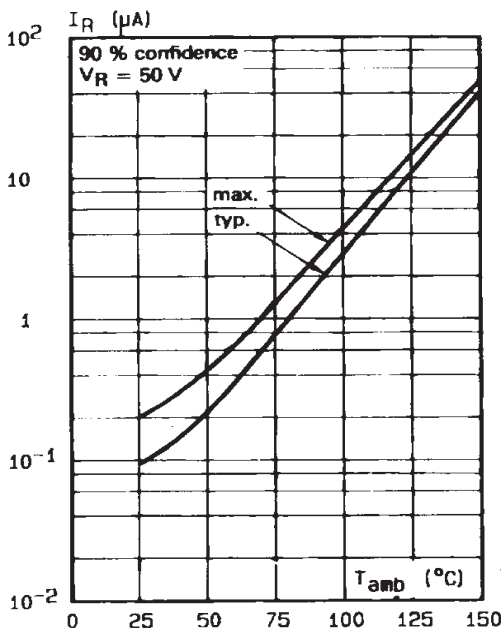
**Fig. 1:** Forward current versus forward voltage at low level (typical values).



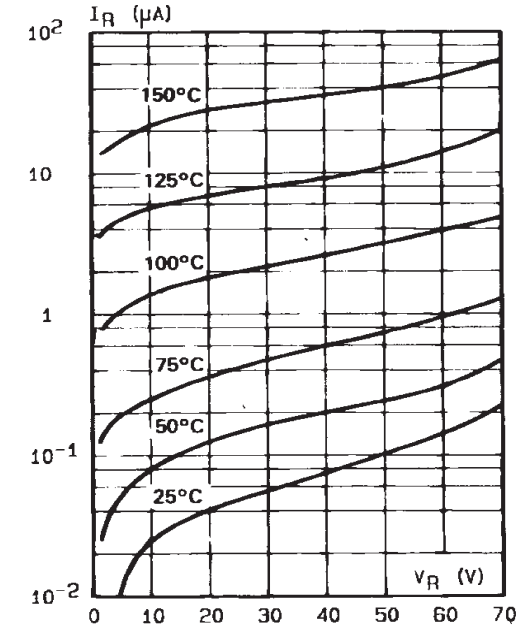
**Fig. 2:** Capacitance  $C$  versus reverse applied voltage  $V_R$  (typical values).



**Fig. 3:** Reverse current versus ambient temperature.

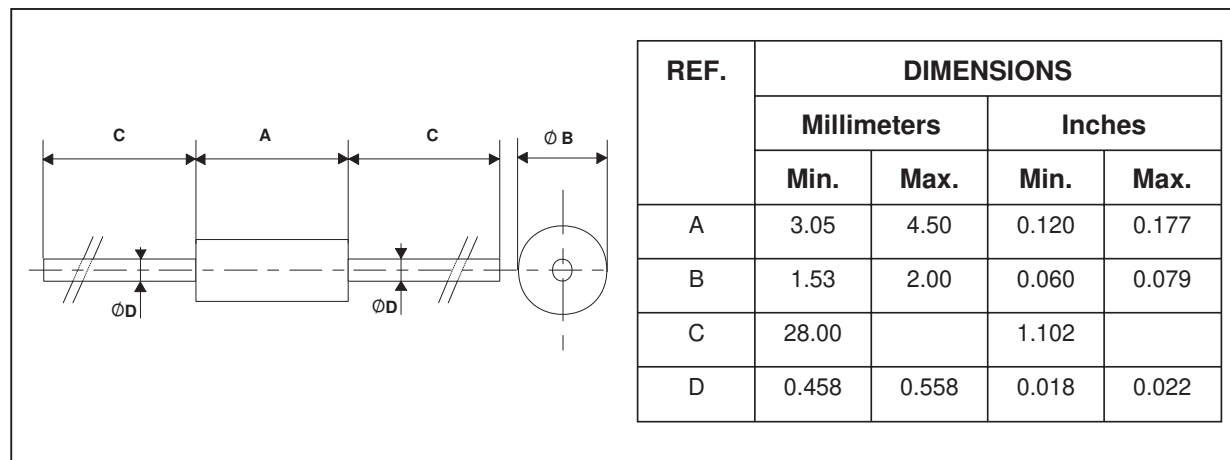


**Fig. 4:** Reverse current versus continuous reverse voltage (typical values).



**PACKAGE MECHANICAL DATA**

DO-35



Cooling method : by convection and conduction

Marking: clear, ring at cathode end.

Weight: 0.15g

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